### **NXP Semiconductors**

**Application Note** 

# Power Management of Xilinx AP SoC using NXP PMIC

Featuring the MMPF0100

## 1 Introduction

This document provides a power management solution for Xilinx Zynq®-7000 System-on-Chips (SoCs), with the Xilinx ZedBoard highlighted as a design example. The ZedBoard is a development board with a broad range of expansion options and the Zynq®7000 as its on-board processor. The document presents the power rail requirements of the Xilinx Zynq®-7000 All Programmable SoCs, many of which are also applicable to Xilinx Field Programmable Gate Arrays (FPGAs). For more details about the specific devices contained in this note, visit www.nxp.com or contact the appropriate product application team.

The PF0100 is NXP's Power Management IC (PMIC) that integrates a total of 14 regulators. Its flexibility in the range of voltage and current options makes it an optimum choice in a wide range of applications. This application note addresses the ability of the PF0100 to provide an optimal solution to the power requirements of a Zynq®-7000 based system taking into account typical I/O, memory and peripherals that are interfaced with the ZedBoard.

NXP analog ICs are manufactured using the SMARTMOS process, a combinational BiCMOS manufacturing flow that integrates precision analog, power functions and dense CMOS logic together on a single cost-effective die.

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## 2 ZedBoard

### 2.1 ZedBoard overview

The Xilinx ZedBoard is an evaluation and development board based on the Xilinx Zynq®-7000 All Programmable SoC (AP SoC). The ZedBoard provides appropriate hardware capabilities for interfacing with a number of peripherals and compatible expansion headers for Xilinx Analog to Digital Convertor (XADC), FPGA Mezzanine Card (FMC) and Diligent Pmod™.

## 2.2 ZedBoard features

The ZedBoard features are:

#### Table 1. ZedBoard features

Feature	Description
Processor	Zynq <sup>®</sup> -7000 AP SoC XC7Z020-CLG484-1
Memory	512 MB DDR3 256 Mb Quad-SPI Flash 4.0 GB SD card
Communication	Onboard USB-JTAG Programming 10/100/1000 Ethernet USB OTG 2.0 and USB-UART
Expansion Connectors	Expansion connectors FMC-LPC connector (68 single-ended or 34 differential I/Os) Five Pmod™ compatible headers (2x6) Agile Mixed Signaling (AMS) header
Clocking	33.33 MHz clock source for PS 100 MHz oscillator for PL
Display	HDMI output supporting 1080p60 with 16-bit, YCbCr, 4:2:2 mode color VGA output (12-bit resolution color) 128 x 32 OLED display
Configuration and Debug	Onboard USB-JTAG interface Xilinx Platform Cable JTAG connector
General Purpose I/O	Eight user LEDs Seven push buttons Eight DIP switches

## 3 Zynq®-7000 SoC

### 3.1 Zynq®-7000 SoC overview

The Xilinx Zynq®-7000 is a family of All Programmable SoCs, aimed at a range of applications from radio and LTE to defense-grade applications. The versatile nature and adaptability of the SoC makes it suitable for multiple applications. The Zynq®-7000 SoC in discussion here, XC7Z020-CLG484-1, has an ARM® Cortex A9 processor with a maximum frequency capability of 667 MHz.

## 3.2 Zynq®-7000 SoC features

The Zynq®-7000 SoC features include:

#### Table 2. Zynq-XC7Z020-CLG484-1 features

Feature	Description
Processor Core	Dual ARM® Cortex™-A9 MPCore™ with CoreSight™
Processor Extensions	NEON™ and Single/Double Precision Floating Point for each processor
Maximum Frequency	667 MHz
L1 Cache	32 KB Instruction, 32 KB Data per processor
L2 Cache	512 KB
On-Chip Memory	256 KB
External Memory Support	DDR3, DDR3L, DDR2, LPDDR2
External Static Memory Support	2x Quad-SPI, NAND, NOR
DMA Channels	Eight (4 dedicated to Programmable Logic)
Peripherals	2x UART, 2x CAN 2.0B, 2x I2C, 2x SPI, 4x 32b GPIO
Peripherals w/ Built-in DMA	2x USB 2.0 (OTG), 2x Tri-mode Gigabit Ethernet, 2x SD/SDIO
Security	RSA Authentication of First Stage Boot Loader, AES and SHA 256b Decryption and Authentication for Secure Boot and for Secure Programmable Logic Configuration
Processing System to Programmable Logic Interface Ports (Primary Interfaces & Interrupts Only)	2x AXI 32b Master, 2x AXI 32b Slave, 4x AXI 64b/32b Memory, AXI 64b ACP, 16 Interrupts
Programmable Logic Cells (Approximate ASIC Gates)	85 k Logic Cells (~1.3 M)
Look Up Tables (LUTs)	53,200
Flip-Flops	106,400
Extensible Block RAM (# 36 Kb Blocks)	560 KB (140)
Programmable DSP Slices (18 x 25 MACCs)	220
Peak DSP Performance (Symmetric FIR)	276 GMACs
Analog Mixed Signal (AMS)/XADC	2 x 12 bit, MSPS ADCs with up to 17 Differential Inputs
Processing System User I/Os (excludes DDR dedicated I/Os)	54
Multi-standards and Multi-voltage Select IOTM Interfaces (1.2 V, 1.35 V, 1.5 V, 1.8 V, 2.5 V, 3.3 V)	200

### 3.3 Power profile requirements

Zynq® Z-7020 has three different sets of voltage requirements, one each for the following: Processing System (PS), Programming Logic (PL) and the XADC. Each set in turn has a number of different voltage level requirements. The voltage profile recommendations from Xilinx are as listed in Table 3

#### Table 3. Recommended voltage levels

Symbol	Description	Min.	Тур.	Max.	Units	Note
DCESSING S	YSTEM (PS)					
V <sub>CCPINT</sub>	PS Internal Supply Voltage	0.95	1.00	1.05	V	
V <sub>CCPAUX</sub>	PS Auxiliary Supply Voltage	1.71	1.80	1.89	V	
V <sub>CCPLL</sub>	PS PLL Supply Voltage	1.71	1.80	1.89	V	
V <sub>CCO_DDR</sub>	PS DDR I/O Supply Voltage	1.14	_	1.89	V	
V <sub>CCO_MIO</sub>	PS MIO I/O Supply Voltage for MIO Banks	1.71	_	3.465	V	
V <sub>PIN</sub>	PS DDR and MIO I/O Input Voltage	-0.20	_	$\begin{array}{c} V_{\text{CCO\_DDR}} \\ + 0.20 \\ V_{\text{CCO\_MIO}} \\ + 0.20 \end{array}$	V	
OGRAMMING	LOGIC (PL)	<u> </u>				
V <sub>CCINT</sub>	PL Internal Supply Voltage	0.95	1.00	1.05	V	
V <sub>CCAUX</sub>	PL Auxiliary Supply Voltage	1.71	1.80	1.89	V	
V <sub>CCBRAM</sub>	PL Block RAM Supply Voltage	0.95	1.00	1.05	V	
V <sub>CCO</sub>	PL Supply Voltage for 3.3 V High Range I/O Banks	1.14	_	3.465	V	
N.	I/O Input Voltage	-0.20	-	V <sub>CCO</sub> + 0.20	V	
V <sub>IN</sub>	I/O Input Voltage (when $V_{CCO}$ = 3.3 V) for $V_{REF}$ and Differential I/O Standards Except TMDS_33	-0.20	-	2.625	V	
V <sub>CCBATT</sub>	Battery Voltage	1.0	_	1.89	V	(1
C		I				
V <sub>CCADC</sub>	XADC supply relative to GNDADC	1.71	1.80	1.89	V	
V <sub>REFP</sub>	Externally supplied reference voltage	1.20	1.25	1.30	V	

Note:

1. These voltage ranges are the recommended supply ranges and are what the power system design in consideration is expected to deliver. Further, to ensure safe operation, the power system should be able to support these voltages at the recommended accuracies summarized in Table 4.

#### Table 4. Required accuracy levels on the different rails

Voltage	Accuracy
V <sub>CCPINT</sub>	±5.0%
V <sub>CCPAUX</sub>	±5.0%
V <sub>CCPLL</sub>	±5.0%
V <sub>CCO_DDR</sub>	±5.0%
V <sub>CCO_MIO</sub>	±5.0%

V <sub>PIN</sub>	_
V <sub>CCINT</sub>	±5.0%
V <sub>CCAUX</sub>	±5.0%
V <sub>CCBRAM</sub>	±5.0%
V <sub>CCO</sub>	±5.0%
V <sub>IN</sub>	_
V <sub>CCBATT</sub>	_
V <sub>CCADC</sub>	±5.0%
V <sub>REFP</sub>	±0.2%, 50 ppm/°C

#### Table 4. Required accuracy levels on the different rails (continued)

The current drawn is an important consideration in power supply designs. A robust power system takes into account worst-case considerations in order to arrive at an optimal value for the maximum current drawn. The currents drawn by the particular device in consideration, XC7Z020-CLG484-1, are documented in Table 5:

#### Table 5. Quiescent currents

Symbol	Description	Current
ICCPINTQ	PS quiescent V <sub>CCPINT</sub> supply current	122 mA
I <sub>CCPAUXQ</sub>	PS quiescent V <sub>CCPAUX</sub> supply current	13 mA
ICCDDRQ	PS quiescent V <sub>CCO_DDR</sub> supply current	4.0 mA
I <sub>CCINTQ</sub>	PL quiescent V <sub>CCINT</sub> supply current	78 mA
I <sub>CCAUXQ</sub>	PL quiescent V <sub>CCAUX</sub> supply current	38 mA
Iccoq	PL quiescent V <sub>CCO</sub> supply current	3.0 mA <sup>(2)</sup>
ICCBRAMQ	PL quiescent V <sub>CCBRAM</sub> supply current	6.0 mA

Total quiescent supply current is 264 mA.

#### Notes

2. In addition to the above mentioned quiescents, **Table 6** shows the minimum current required by the Zynq® device for proper power-on and configuration.

#### Table 6. Power-on currents<sup>(3)</sup>

Symbol	Description	Current
ICCPINTMIN	Minimum power-on V <sub>CCPINT</sub> supply current	192 mA
ICCPAUXMIN	Minimum power-on V <sub>CCPAUX</sub> supply current	53 mA
ICCDDRMIN	Minimum power-on $V_{\rm CCO\_DDR}$ supply current	104 mA
ICCINTMIN	Minimum power-on V <sub>CCINT</sub> supply current	148 mA
I <sub>CCAUXMIN</sub>	Minimum power-on V <sub>CCAUX</sub> supply current	98 mA
I <sub>CCOMIN</sub>	Minimum power-on $V_{CCO}$ supply current	453 mA
ICCBRAMMIN	Minimum power-on V <sub>CCBRAM</sub> supply current	46 mA
Total power-on curre	ent is 1094 mA.	

#### Notes

3. The currents are calculated assuming one DDR bank and five HR I/O banks. The values of  $I_{CCDDRMIN}$  and  $I_{CCOMIN}$  increase or decrease by 100 mA and 90 mA per bank respectively for a corresponding increase or decrease in the number of banks.

The Xilinx Power Estimator (XPE) tool acts as a very important step in the pre-implementation phase of the design. Once the device startup currents are met, the current demand on each rail must be satisfied. The XPE provides an estimate of these currents, based on user inputs, and the worst case estimate helps decide the power system configuration.

**Table 7** provides an approximate estimate of the current drains on each of the supply rails, obtained from the XPE. This estimate is based on the ZedBoard's utilization of the Zynq<sup>®</sup>-7000 device.

Symbol	Description	Current
I <sub>CCPINT</sub>	Current drawn on V <sub>CCPINT</sub> supply	0.8 A
I <sub>CCPAUX</sub>	Current drawn on V <sub>CCPAUX</sub> supply	0.04 A
I <sub>CCDDR</sub>	Current drawn on V <sub>CCO_DDR</sub> supply	0.4 A
I <sub>CCINT</sub>	Current drawn on V <sub>CCINT</sub> supply	1.9 A
I <sub>CCAUX</sub>	Current drawn on V <sub>CCAUX</sub> supply	0.5 A
I <sub>CCPLL</sub>	Current drawn on V <sub>CCPLL</sub> supply	0.11 A
ICCBRAM	Current drawn on V <sub>CCBRAM</sub> supply	0.1 A

#### Table 7. Current drain on supplies

### 3.4 Power-on sequence

The processor-centric approach of the Zynq<sup>®</sup> SoC requires the processor to be powered up first. This results in the V<sub>CCINT</sub> rail occupying top priority in the power-up sequence. The PS and PL rails can be powered up independent of each other as they are isolated from each other in order to prevent damage. The device specification recommends that the power-off sequence be the reverse of the power-on sequence. **Figure 1** shows a recommendation for the power-on sequence.

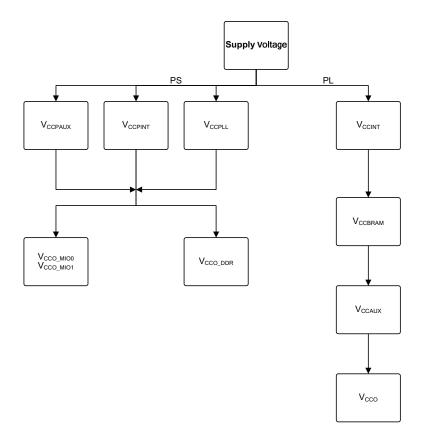
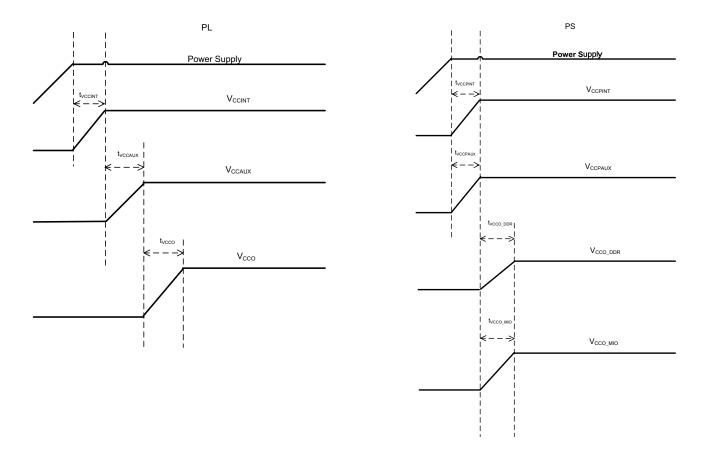


Figure 1. Power-on sequence

**Table 8** and **Figure 2** illustrate the constraints on the ramp times.  $t_{VCCO2VCCAUX}$  is the time for which the difference between the I/O's supply in the PS or PL ( $V_{CCO\_MIO}$  or  $V_{CCO}$ ) and the corresponding auxiliary supply ( $V_{CCPAUX}$  or  $V_{CCAUX}$ ) can exceed 2.625 V.  $t_{VCCO2VCCAUX}$  has to be below 800 ms when the junction temperature is 85 °C and below 300 ms for a junction temperature of 125 °C. This constraint has to be followed to maintain safe operation of the device.

Table 8. Power supply ramp ti
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Symbol	Description	Min	Мах	Units
t <sub>VCCPINT</sub>	Ramp time from GND to 90% of V <sub>CCPINT</sub>	0.2	50	ms
t <sub>VCCPAUX</sub>	Ramp time from GND to 90% of $V_{CCPAUX}$	0.2	50	ms
t <sub>VCCO_DDR</sub>	Ramp time from GND to 90% of V <sub>CCO_DDR</sub>	0.2	50	ms
<sup>t</sup> vcco_мю	Ramp time from GND to 90% of V <sub>CCO_MIO</sub>	0.2	50	ms
t <sub>VCCINT</sub>	Ramp time from GND to 90% of V <sub>CCINT</sub>	0.2	50	ms
t <sub>vcco</sub>	Ramp time from GND to 90% of $V_{CCO}$	0.2	50	ms
t <sub>VCCAUX</sub>	Ramp time from GND to 90% of V <sub>CCAUX</sub>	0.2	50	ms



#### Figure 2. Ramp times

It is essential for the designer to keep in mind the voltage and current levels and accuracy, the power supply sequence, the ramp, and delay times, to ensure safe operation of the system.

## 4 MMPF0100

The PF0100 SMARTMOS Power Management Integrated Circuit (PMIC) provides a highly programmable/configurable architecture, with fully integrated power devices and minimal external components. With up to six buck converters, six linear regulators, Real Time Clock (RTC) supply, and coin-cell charger, the PF0100 can provide power for a complete system, including applications processors, memory, and system peripherals, in a wide range of applications.

Features:

- · Four to six buck converters, depending on configuration
  - Single/parallel options
  - DDR termination tracking mode option
- Boost regulator to 5.0 V output
- Six general purpose linear regulators
- · Programmable output voltage, sequence, and timing
- OTP (One Time Programmable) memory for device configuration
- · Coin cell charger and RTC supply
- DDR termination reference voltage
- · Power control logic with processor interface and event detection
- I<sup>2</sup>C control
- Individually programmable ON, OFF, and Standby modes

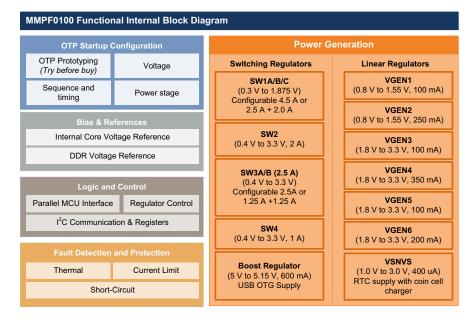


Figure 3. Functional internal block diagram of the MMPF0100

The number of available voltage options from the MMPF0100 PMIC at different currents enables it to provide to the different power needs of the ZedBoard. The buck regulators can be configured in four different modes, depending on the requirement. Table 9 shows a configuration where the maximum number of rails are available, at reduced currents, whereas Table 10 shows a configuration where only four rails are available but can support higher current demands.

Regulator Name	Output Voltage Range	DC Current Load Capability
SW1AB	0.3 V to 1.875 V	2.5 A
SW1C	0.3 V to 1.875 V	2.0 A
SW2	0.4 V to 3.3 V	2.0 A
SW3A	0.4 V to 3.3 V	1.25 A
SW3B	0.4 V to 3.3 V	1.25 A
SW4	0.4 V to 3.3 V	1.0 A

#### Table 9. Six independent buck regulators

#### Table 10. Four independent buck regulators

Regulator Name	Output Voltage Range	DC Current Load Capability
SW1ABC	0.3 V to 1.875 V	4.5 A
SW2	0.4 V to 3.3 V	2.0 A
SW3AB	0.4 V to 3.3 V	2.5 A
SW4	0.4 V to 3.3 V	1.0 A

SW1AB and SW1C may be combined independent of SW3A and SW3B and vice versa. This leads to two different configurations, with five regulators each, shown in Table 11 and Table 12. The PF0100 used in this application is programmed according to the configuration shown in Table 11.

#### Table 11. Five independent buck regulators - option 1

Regulator Name	Output Voltage Range	DC Current Load Capability
SW1ABC	0.3 V to 1.875 V	4.5 A
SW2	0.4 V to 3.3 V	2.0 A
SW3A	0.4 V to 3.3 V	1.25 A
SW3B	0.4 V to 3.3 V	1.25 A
SW4	0.4 V to 3.3 V	1.0 A

#### Table 12. Five independent buck regulators - option 2

Regulator Name	Output Voltage Range	DC Current Load Capability
SW1AB	0.3 V to 1.875 V	2.5 A
SW1C	0.3 V to 1.875 V	2.0 A
SW2	0.4 V to 3.3 V	2.0 A
SW3AB	0.4 V to 3.3 V	2.5 A
SW4	0.4 V to 3.3 V	1.0 A

Of particular note are the One Time Programmable (OTP) mode and the Try Before Buy (TBB) mode. The OTP mode allows you to pre-program the default values for the PF0100 registers at start up. The TBB mode gives you the option of trying out various settings before the registers are actually written to with their values. The TBB mode is especially useful when the power system is being designed or there are modifications needed to an existing solution. You can also shift between Pulse Width Modulation (PWM), Pulse Frequency Modulation (PFM) and Auto Pulse Skip Mode (APS) for the buck regulators.

The Power Stage Control registers can be used to reduce the required inductor current limit when the regulators are not operating at their rated output currents, enabling use of smaller inductors. This provides a significant advantage to the PF0100 as there may be a number of applications where not all regulators are exercised to their current limits. Furthermore, the Dynamic Voltage Scaling (DVS) feature eliminates the need for a resistor divider network in the feedback loop of the buck regulators, thereby reducing the number of external components required.

## 5 Power solution for the ZedBoard

Before a power solution can be installed, it is important to have an estimate of the various voltage rails and the current drawn on each of them. Although the Zynq®-7000 SoC section provides a summary of the voltage domains necessary for proper operation of the Zynq® device, recommended settings allow—and in some cases, require—some of the voltages to be combined and powered by the same rail, whenever they are of the same voltage levels. Furthermore, there may be a need for multiple  $V_{CCO}$ ,  $V_{CCO\_MIO}$ , and  $V_{CCO\_DDR}$  rails, depending on the voltage requirements of the peripherals. This highlights the need for doing a detailed analysis of the voltage level requirements for the case being implemented.

NXP recommends using the Xilinx Power Estimator (XPE) tool to arrive at an estimate for the particular case under consideration. Although this yields only an approximate estimate, it is usually accurate enough for the pre-synthesis phase and it provides the designer with a general idea of the current requirements. The Power Analyzer tool provides a more accurate estimate once the design is implemented. Furthermore, you can import data from the Power Analyzer tool to the XPE to compare with the pre-implementation analysis and to take corrective measures if necessary.

Designers should be aggressive in doing worst-case estimates while keeping in mind that over-designing may impact cost. The different use cases may vary significantly from the worst-case estimate.

Settings				s	umma	ry		
D	evice	Total On Ch	Total On-Chip Power 1.93			0% •		0.000W
Family	Zyng-7000	Total On-Ch	rotal on-onp Power			4% •		0.068W
Device	XC7Z020	Junction Ter	nperature	34.3	°C	81%		1.566W
Package	CLG484	Thermal Ma	gin	50.7°C	10.0W	16%		0.303W
Speed Grade	-1	Effective OJA		4	.8 °C/W	Pow er supplied to off	f-chip devices	0.000W
Temp Grade	Commercial							
Process	Maximum	On-Chip	Power			- Power	Supply	
		Resou	rce	Pow	er	Source	Voltage	otal (A)
Characterization	Production, v1.0, 2012-07-11		Jump to sheet)	(W)	(%)	V <sub>CCINT</sub>	1.000	0.104
			CLOCK	0.034	2	V <sub>CCBRAM</sub>	1.000	0.040
Env	vironment		LOGIC	0.004	0	V <sub>CCAUX</sub>	1.800	0.141
Junction Temperature	User Override		BRAM	0.005	0	V <sub>CCAUX</sub> IO		
Ambient Temp	25.0 °C	Core	DSP	0.000	0	V <sub>cco</sub> 3.3V	3.300	0.091
Effective OJA	User Override	Dynamic	PLL	0.000	0	V <sub>CCO</sub> 2.5V	2.500	0.091
Airflow	250 LFM		MMCM	0.208	11	V <sub>cco</sub> 1.8V	1.854	
Heat Sink	Medium Profile		Other	0.000	0	V <sub>cco</sub> 1.5V	1.500	
OSA	4.6 °C/W					V <sub>cco</sub> 1.35V	1.350	
Board Selection	Medium (10"x10")	VO	ю	0.068	4	V <sub>cco</sub> 1.2V	1.200	
# of Board Layers	8 to 11	Transceiver				-	1.800	
ΘJB						-	1.000	
Board Temperature		PS Dynamic	PS	1.314	68	-	1.200	
		Static		0.161	8		1.000	0.494
	ementation	PL Static		0.142	7		1.800	0.055
Usage/Optimization	Default						1.800	0.119
							1.500	0.514
Messages							1.800	0.004
wessages						V <sub>CC0_MI01</sub>	1.800	0.005

Figure 4. Power estimation data for use case 1

**Figure 4** shows the power supply summary obtained from XPE for a particular use case implemented in the ZedBoard. It also involves the use of HDMI, I<sup>2</sup>S audio, I<sup>2</sup>C and GPIO pins, and runs PetaLinux OS from the SD card.

_ Settings		_			Si	umma	ry			
Ľ	evice	Tata		ip Power	2.023	10/		0% =		0.000W
<sup>=</sup> amily	Zynq-7000	Tota	ron-cn	ip Power	2.023	~		38% •		0.775W
Device	XC7Z020	Junct	Junction Temperature		81.8 °	°C		18% -		0.370W
Package	CLG484	The	rmal Mai	gin	3.2°C	0.7W		43% =		0.878W
Speed Grade	-1	Effec	ctive OJA	·	4	.8 °C/W	Pow	er supplied to off	-chip devices	0.000W
Temp Grade	Commercial									
Process	Maximum	OI	n-Chip	Power -			1	Power	Supply-	
			Resou	irce	Pow	er 💧		Source	Voltage T	otal (A)
Characterization	Production, v1.0, 2012-07-11			Jump to sheet)	(VV)	(%)			1.000	0.384
				CLOCK	0.001	О			1.000	0.040
Env	vironment			LOGIC	0.000	о		VCCAUX	1.800	0.377
lunction Temperature	User Override			BRAM	0.000	о		V <sub>CCAUX</sub> IO		
Ambient Temp	72.1 °C		Core	DSP	0.000	0		V <sub>cco</sub> 3.3V	3.300	
Effective OJA	User Override	Dy	namic	PLL	0.100	5		V <sub>CCO</sub> 2.5V	2.500	
Airflow	250 LFM			MMCM	0.000	0		V <sub>cco</sub> 1.8V	1.800	0.091
Heat Sink	Medium Profile			Other	0.268	13		V <sub>cco</sub> 1.5V	1.575	0.288
ΘSA	4.6 °C/W							V <sub>cco</sub> 1.35V	1.350	
Board Selection	Medium (10"x10")		٧O	ю	0.775	38		V <sub>cco</sub> 1.2V	1.200	
# of Board Layers	8 to 11	Trapa	ceiver					-	1.800	
ΘJB			Cerver					-	1.000	
Board Temperature		PSC	ynamic	PS	0.000	о			1.200	
			Static		0.450	22			1.000	0.402
	ementation	PL	Static		0.429	21			1.800	0.021
Jsage/Optimization	Default	L					·		1.800	0.006
		_				_		V <sub>CCO_DDR</sub>	1.500	
Messages									1.800	
								V <sub>CC0 MI01</sub>	1.800	0.025

Figure 5. Power estimation data for use case 2

Figure 5 shows the power supply summary obtained from XPE for an use case that portrays the use of HDMI and DDR3 memory.

/s			Si	umma	ry 🗕			
Device	otal On-Chi	in Power	5.814	w		0%		0.000W
Zynq-7000		ip Fower	5.014			25%		1.438W
XC7Z020 Ju	unction Ten	nperature	52.8	°C		66%		3.837W
CLG484	Thermal Mar	gin	32.2°C	6.2W		9%		0.538W
deE	Effective OJA	· · · · · · · · · · · · · · · · · · ·	4	.8 °C/W	Power	supplied to of	f-chip devices	0.000W
e Commercial								
Maximum	On-Chip	Power				Power	Supply	
Jsed	Resou	rce	Pow	er		Source	Voltage	Fotal (A)
ation Production, v1.0, 2012-07-11		Jump to sheet)	(W)	(%)		ссілт	1.050	1.903
		CLOCK	0.115	2	V	CCBRAM	1.050	0.093
Environment		LOGIC	0.393	7	V	CCAUX	1.890	0.483
nperature 🗌 User Override		BRAM	1.117	19	$\sim$	ccaux_io		
<u>קו</u> 25.0 °C	Core	DSP	0.136	2	<u> </u>	′ <sub>CCO</sub> 3.3V	3.450	0.168
A User Override	Dynamic	PLL	0.106	2	<u> </u>	′ <sub>CCO</sub> 2.5V	2.625	0.091
250 LFM		ММСМ	0.219	4		′ <sub>CCO</sub> 1.8V	1.890	0.091
Medium Profile		Other	0.332	6		′ <sub>cco</sub> 1.5V	1.575	0.306
4.6 °C/W						′ <sub>CCO</sub> 1.35V	1.350	
tion Medium (10"x10")	٧O	Ю	1.438	25		′ <sub>CCO</sub> 1.2V	1.260	
Layers 8 to 11	ansceiver					-	1.850	
	ansceivei						1.030	
perature P	S Dynamic	PS	1.419	24		-	1.230	
	Static		0.269	5		, CCPINT	1.050	0.810
PL Implementation	PL Static		0.269	5	<u> </u>	CCPAUX	1.890	0.040
nization Default						, CCPLL	1.890	0.112
						CCO_DDR	1.500	0.366
anes .							3.450	0.013
							1.890	0.008
	t Request (We to XPE (video)		Wh	itepaper -	L ×		1.890 1.890 Estimator Us case Power E	

Figure 6. Worst-case estimate from XPE

**Figure 6** shows the worst-case power estimates for the ZedBoard. The calculations are made using exaggerated activity rates and loads in order to account for unexpected user anomalies. Notice that the current capabilities of the PF0100 offer a satisfactory level of tolerance above this calculated limit.

Furthermore, some of the LDOs on the PF0100 are left unused and are available for other system uses.

While these cases show the PF0100's compatibility with the Zynq® XC7Z020 on the ZedBoard, you can also use them to power other platforms based on the Z-7020 or other Zynq® SoCs.

_ Settings					Sui	nmar	y			
D	evice		Total On Chi	n Dowor	4.344 V			0% •		0.000W
Family	Zynq-7000		Total On-Chi	Total On-Chip Power		v		20% •		0.883W
Device	XC7Z010		Junction Ten	nperature	75.1 °C			64% •		2.789W
Package	CLG400		Thermal Mar	gin	9.9°C 0	.8W		15% •		0.672W
Speed Grade	-1		Effective OJA		11.5	°C/W	Pow	er supplied to off-	chip devices	0.000W
Temp Grade	Commercial	-								
Process	Maximum	Г	— On-Chip	Power -			ſ	– Power	Supply_	
			Resou	rce	Power	r ไ		Source	Voltage	otal (A)
Characterization	Production, v1.0, 2012-07-11		(	Jump to sheet)	(W)	(%)		V <sub>CCINT</sub>	1.050	0.930
				CLOCK	0.056	1		V <sub>CCBRAM</sub>	1.050	0.047
Env	ironment			LOGIC	0.130	3		V <sub>CCAUX</sub>	1.890	0.470
Junction Temperature	User Override			BRAM	0.479	11		V <sub>CCAUX_IO</sub>		
Ambient Temp	25.0 °C		Core	DSP	0.049	1		V <sub>CCO</sub> 3.3V	3.450	0.091
Effective OJA	User Override		Dynamic	PLL	0.106	2		V <sub>CCO</sub> 2.5V	2.625	0.091
Airflow	250 LFM			MMCM	0.219	5		V <sub>CCO</sub> 1.8V	1.890	0.091
Heat Sink	None			Other	0.332	8		V <sub>cco</sub> 1.5V	1.575	0.306
ΘSA								V <sub>CCO</sub> 1.35V	1.350	
Board Selection	Medium (10"x10")		VO	Ю	0.883	20		V <sub>CCO</sub> 1.2V	1.200	
# of Board Layers	8 to 11		Τ						1.800	
ΘJB			Transceiver						1.000	
Board Temperature			PS Dynamic	PS	1.419	33			1.200	
			Static		0.444	10		V <sub>CCPINT</sub>	1.050	0.977
	ementation		PL Static		0.228	5		V <sub>CCPAUX</sub>	1.890	0.040
PL Imple								V <sub>CCPLL</sub>	1.890	0.112
	Default	L						M		0.000
	Default							V <sub>CCO_DDR</sub>	1.500	0.366
PL Imple Usage/Optimization Messages	Default	, L						VCCO_DDR V <sub>CCO_MIO0</sub> V <sub>CCO_MIO1</sub>	1.500 3.450 1.890	0.366

#### Figure 7. XPE estimate for Z-7010

The power demand of the Z-7010, presented by the estimate in Figure 7, is met by the PF0100.

### 5.1 Power tree design

The supply to the ZedBoard is from a 12 V barrel-jack connector. This is stepped down to 3.6 V in order to meet the input side supply requirement of the PF0100.

Following Xilinx recommendations:

- V<sub>CCINT</sub> and V<sub>CCBRAM</sub> should be connected to the same supply
- V<sub>CCPAUX</sub>, V<sub>CCPLL</sub> and the V<sub>CCO</sub>, V<sub>CCO\_MIO</sub>, V<sub>CCO\_DDR</sub> rails which have the same voltages may be powered from the same rails
- V<sub>CCAUX</sub> and V<sub>CCO</sub> may be powered from the same rails if they have the same recommended voltages

Taking into account the recommendations and the ZedBoard needs, the required rails are:

- One 1 V rail for V<sub>CCPINT</sub>, V<sub>CCINT</sub> and V<sub>CCBRAM</sub>
- One 1.8 V rail for V<sub>CCAUX</sub>, V<sub>CCPAUX</sub>, V<sub>CCPLL</sub>, V<sub>CCBATT</sub> and V<sub>CCO\_MIO1</sub> (supplies to USB-UART, USB-OTG, SD Card, Push buttons and Ethernet)
- One 3.3 V rail for V<sub>CCO</sub> (supplies to JTAG, LEDs, OLED display, HDMI, VGA, Pmod and Audio codec) and V<sub>CCO\_MIO0</sub> (supplies to Pmod and QSPI)
- One adjustable 3.3/2.5/1.8 V rail for V<sub>CCO</sub> (supplies to FMC, XADC, push buttons and switches)
- One 5 V rail for USB OTG, HDMI and audio codec
- One 1.5 V rail for V<sub>CCO DDR</sub>
- One 0.75 V rail for V<sub>TT</sub> DDR (DDR3 termination voltage)
- One 1.8 V rail for V<sub>CCADC</sub>
- One 1.25 V rail for V<sub>REFP</sub> (low current, high accuracy)

The ZedBoard power requirements and the corresponding supplies are summarized in Table 13.

Rail	Voltage level	Current drawn	Supply
V <sub>CCINT</sub>	1.0 V	4.5 A	SW1ABC (PF0100)
V <sub>CCAUX</sub>	1.8 V	1.0 A	SW3B (PF0100)
V <sub>CCO1</sub>	3.3 V	3.0 A	MC34713
V <sub>CCO2</sub>	3.3/2.5/1.8 V	2.0 A	SW2 (PF0100)
V <sub>CC5V0</sub>	5.0 V	0.6 A	SWBST (PF0100)
V <sub>CCO_DDR</sub>	1.5 V	1.0 A	SW3A (PF0100)
V <sub>TT_DDR</sub>	0.75 V	1.0 A	SW4 (PF0100)
V <sub>CCADC</sub>	1.8 V	0.1 A	VGEN4 (PF0100)
V <sub>REFP</sub>	1.25 V	0.005 A	Reference generator

#### Table 13. Power requirements for ZedBoard

The buck regulators in the PF0100 may be configured as five independent regulators to power  $V_{CCINT}$ ,  $V_{CCAUX}$ ,  $V_{CCO2}$ ,  $V_{CCO_DDR}$  and  $V_{TT\_DDR}$  rails. The PF0100 VTT tracking mode is software enabled. This allows the  $V_{TT\_DDR}$  rail to automatically track half of  $V_{CCO\_DDR}$  if they are connected to SW4 and SW3A respectively. VGEN4 may be used to power  $V_{CCADC}$ . The boost regulator in the PF0100 is utilized to supply the  $V_{CC5V0}$  rail.

The  $V_{CCO1}$  rail requires a buck converter to convert the available 3.6 V to 3.3 V, while being capable of supplying 3 A. Because most peripherals are supplied through this rail, the current being drawn may vary. Therefore, to ensure safe operation, both this rail and the  $V_{CCINT}$  rail are provided with sufficient margins. The NXP Switched-mode Power Supply (SMPS) MC34713 provides a good option for achieving this. The MC34713 is a highly integrated, space efficient, low cost, single synchronous buck switching regulator with integrated N-channel power MOSFETs. It is a high performance point-of-load (PoL) power supply with the ability to track an external reference voltage in different configurations. Its high-efficient 5.0 A continuous output current capability combined with its voltage tracking/sequencing ability and tight output regulation, makes it ideal as a single power supply. The Shutdown pin on the MC34713 is controlled to ensure that the supply from this rail is compatible with the sequence constraints.

The power-off sequence is enforced by software. PF0100 can be communicated to via I2C. Appropriate register settings are sent over I2C so that the rails are turned off in the recommended sequence.

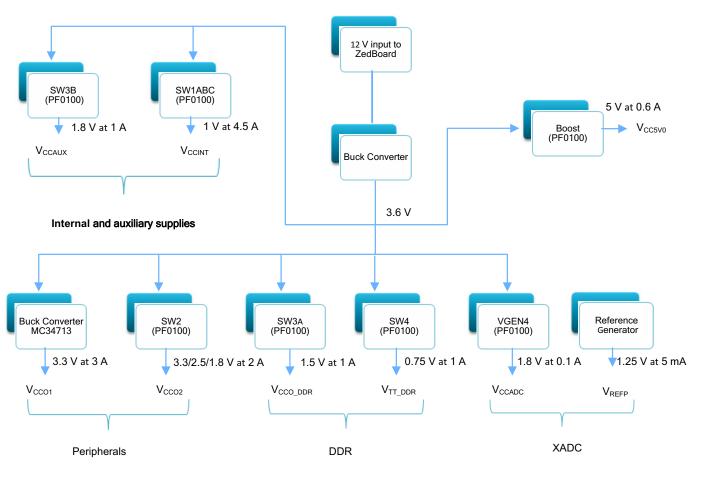


Figure 8. Power tree

The ZedBoard's power tree is represented in Figure 8.

### 5.2 PF0100 interface with Zynq®

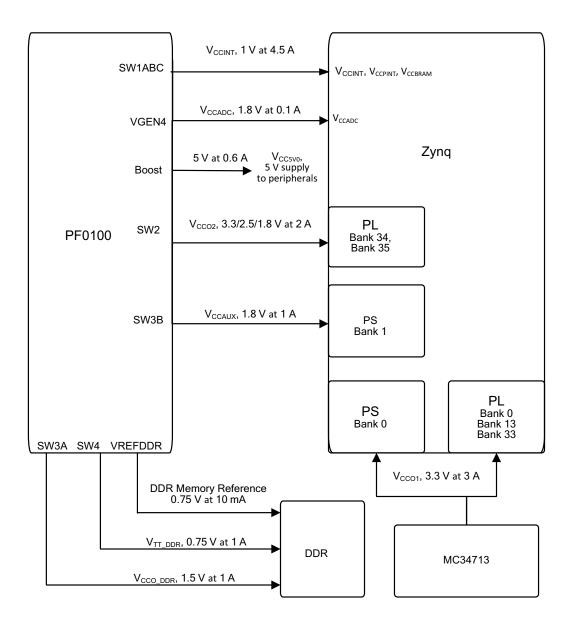
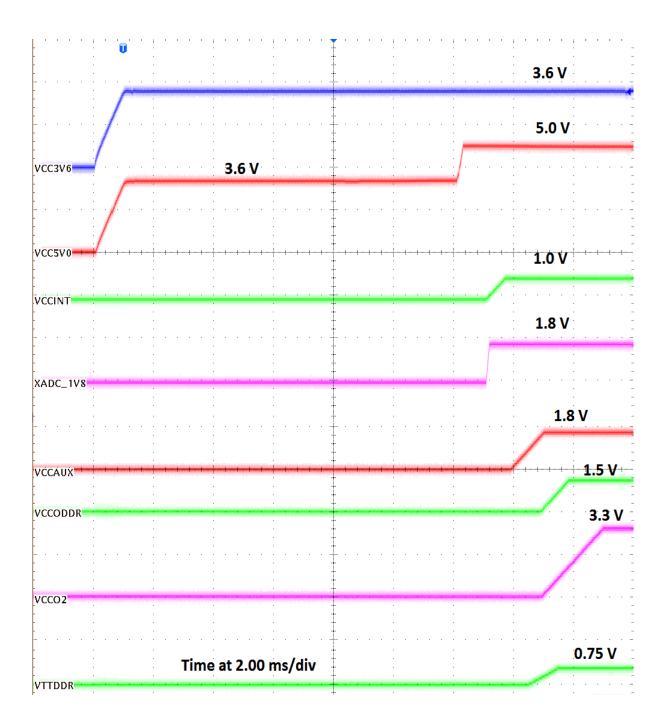




Figure 9 demonstrates the power bank assignments and the interface connections from the PF0100 to the XC7Z010-CLG484-1 IC on the ZedBoard.



#### Figure 10. Power rails generated using the PF0100

**Figure 10** shows the PF0100 used to supply the seven power rails required by the on-board Zynq® processor. To control ramp times, modify the DVS settings in the PF0100. A DVS setting of 3.125 mv/usec and a sequencer setting of 1.00 ms ensures that the start-up requirements are met. Using the PF0100's Power-OK output to control the MC34713's Shut-down mode input pin ensures that the  $V_{CCO1}$  signal powers up last in the sequence. Because  $V_{CCO1}$  is a peripheral rail, this complies with the power-on recommendations for the Zynq®-7020. Furthermore, the PF0100 settings, including output voltages, start-up sequences, frequency, and switching mode (PWM, APS, PFM), are completely configurable on-the-fly using I<sup>2</sup>C. Table 14 illustrates the ramp time and sequence configurations from the demonstration board.

Voltage rail	Sequence position	Rise time - GND to 90% (in ms)
V <sub>CC3V6</sub>	0	0.834
V <sub>CC5V0</sub> <sup>(4)(5)</sup>	1	0.103
V <sub>CCINT</sub>	2	0.258
V <sub>CCADC</sub>	3	0.225
V <sub>CCAUX</sub>	4	0.685
V <sub>CCODDR</sub>	4	0.539
V <sub>TT_DDR</sub>	4	0.616
V <sub>CC02</sub>	4	1.434
V <sub>CC01</sub>	5	2.710

#### Table 14. Ramp timing and sequence settings of individual rails on the hardware board

4. Because the 5 V rail supplies peripherals like USB-OTG and does not directly impact the operation of Zynq®, it is powered on before other rails 5. The ramp time for the 5 V rail is measured from 3.6V to 90% and not from GND to 90%

## 5.3 Schematics

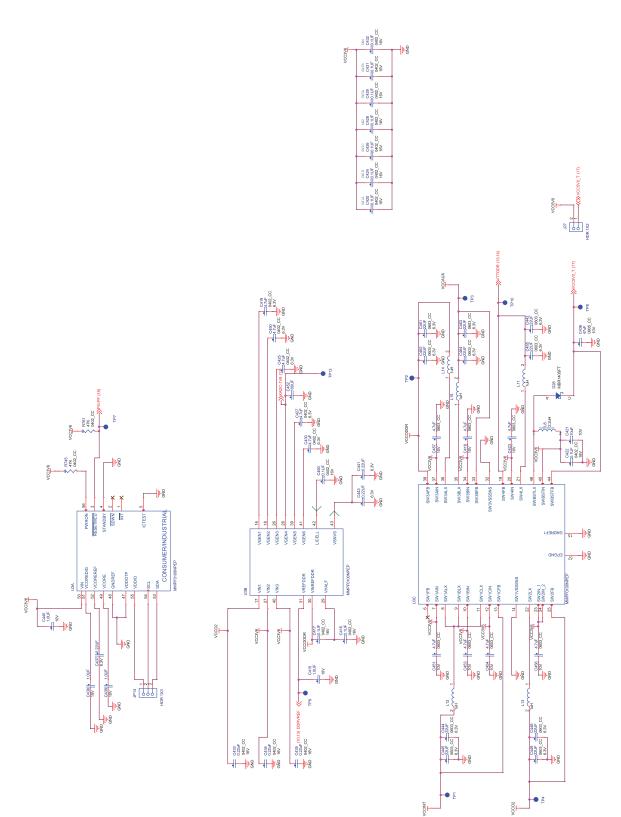


Figure 11. MMPF0100

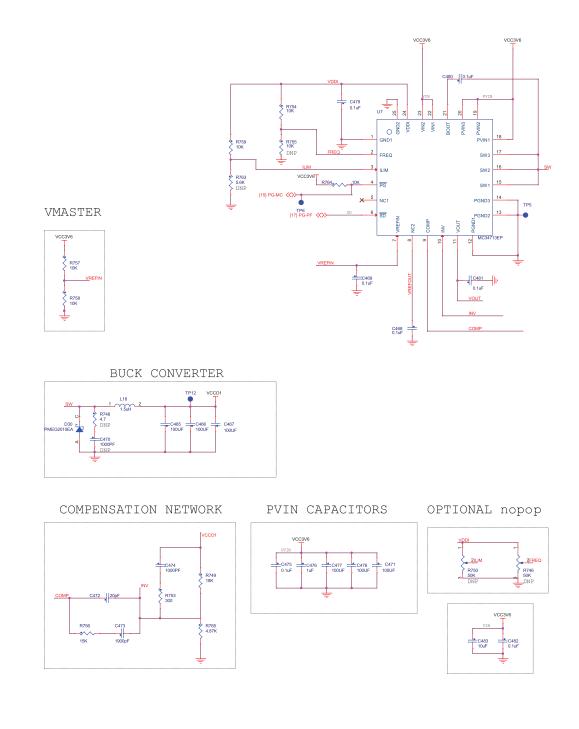


Figure 12. MC34713

NOTE

For full schematics and layout, please contact an NXP representative.

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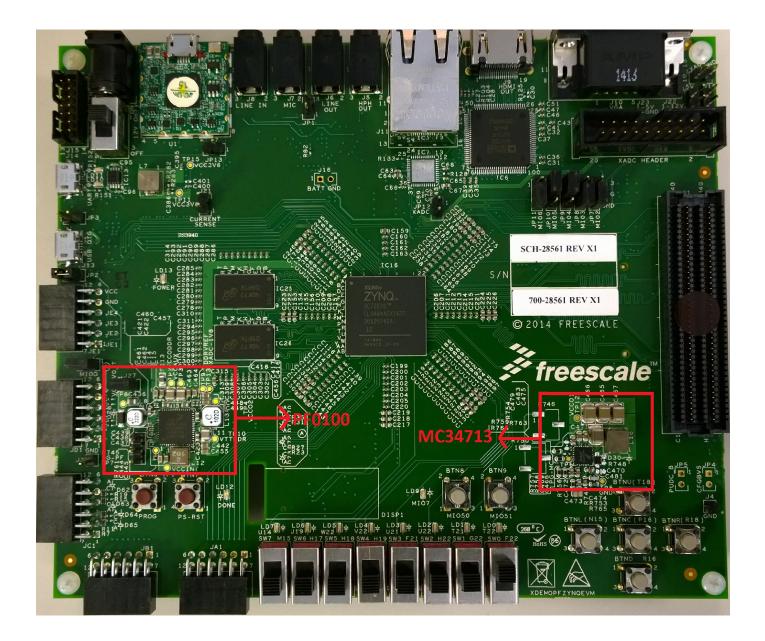


Figure 13. Zynq®-7020 board powered by PF0100

## 6 Conclusion

This Application Note offers an example of an optimal power management solution using the Xilinx ZedBoard development board in conjunction with the NXP's PF0100 Power Management IC (PMIC). The PF0100 PMIC is an ideal candidate for the power management of Xilinx Zynq® AP SoCs, particularly when used with the ZedBoard. The solution discussed in this document may be tweaked to provide a power solution for other systems based on Zynq® devices. Some distinct advantages of using the PF0100 are:

- The PF0100 PMIC-based power solution discussed above results in a design that uses a low number of discrete components. This offers the possibility of an overall reduction in silicon real-estate and a corresponding reduction in cost.
- The start-up sequence and output voltages can be enforced using software rather than passive components or other external circuitry. This ensures more accurate control
- Enforcing the Power Stage Control and DVS ensures a reduction in the inductor current limits and sizes, and improves efficiency and stability
- The PF0100 has a built-in VTT tracking mode which eliminates the need for an external DDR voltage termination component
- The VREFDDR option in the PF0100 may be utilized for DDR3 reference voltage
- The unused LDOs in the PF0100 are available for other user demands

## 7 References

Following are URLs where you can obtain information on related NXP products and application solutions:

Support Pages	Description	URL
MMPF0100	Data Sheet	http://www.nxp.com/files/analog/doc/data_sheet/MMPF0100.pdf
MC34713	Data Sheet	www.nxp.com/files/analog/doc/data_sheet/MC34713.pdf
MMPF0100	Product Summary Page	http://www.nxp.com/webapp/sps/site/prod_summary.jsp?code=MMPF0100
	Analog Home Page	http://www.nxp.com/analog
	Xilinx Home Page	http://www.xilinx.com

### 7.1 Support

Visit www.nxp.com/support for a list of phone numbers within your region.

## 7.2 Warranty

Visit www.nxp.com/warranty for a list of phone numbers within your region.

## 8 Revision History

Revision	Date	Description
1.0	9/2014	Initial release
2.0	3/2015	Updated with results from hardware board
2.0	7/2016	Updated to NXP document form and style

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